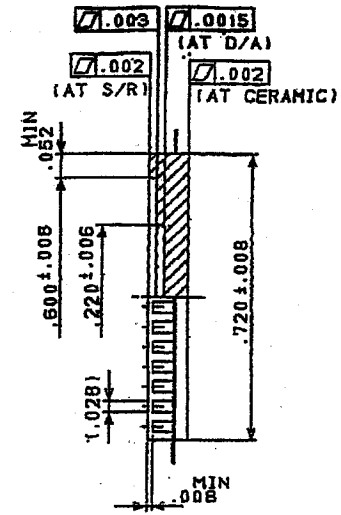
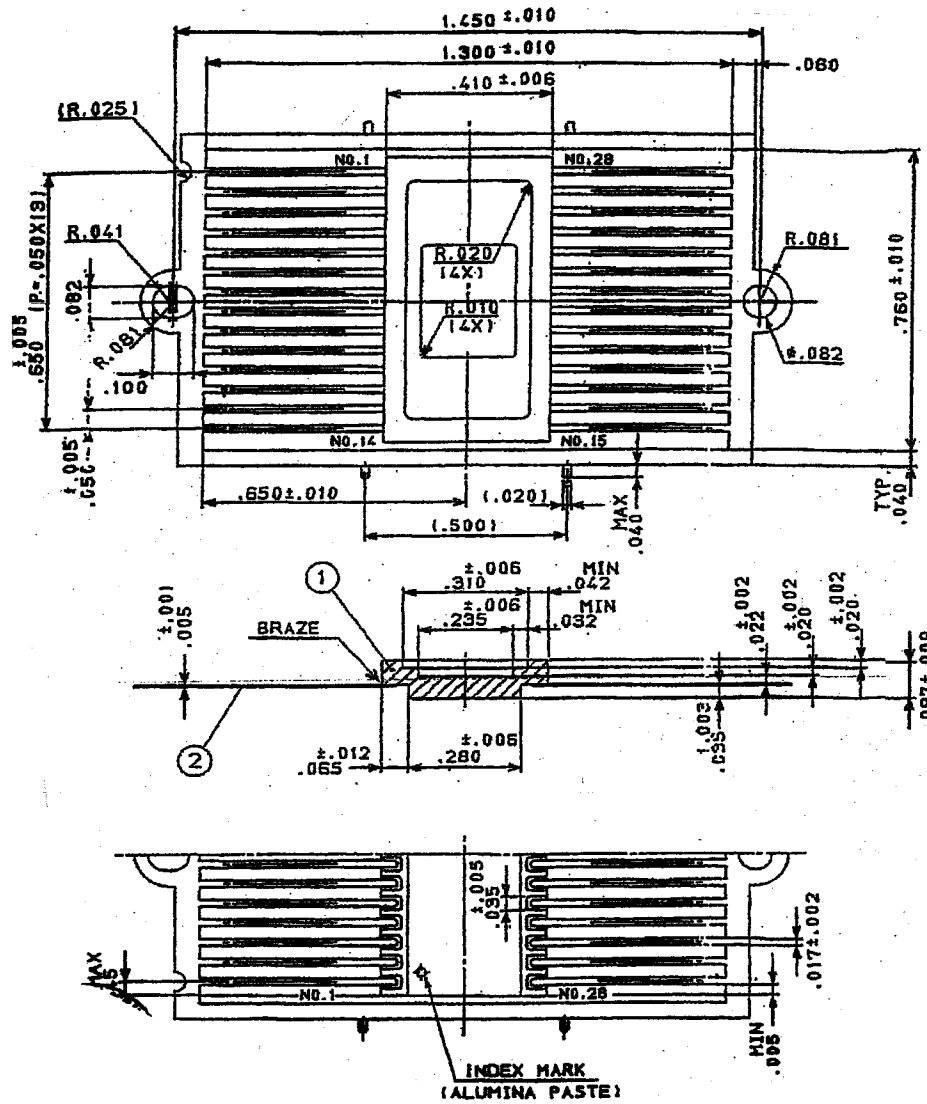


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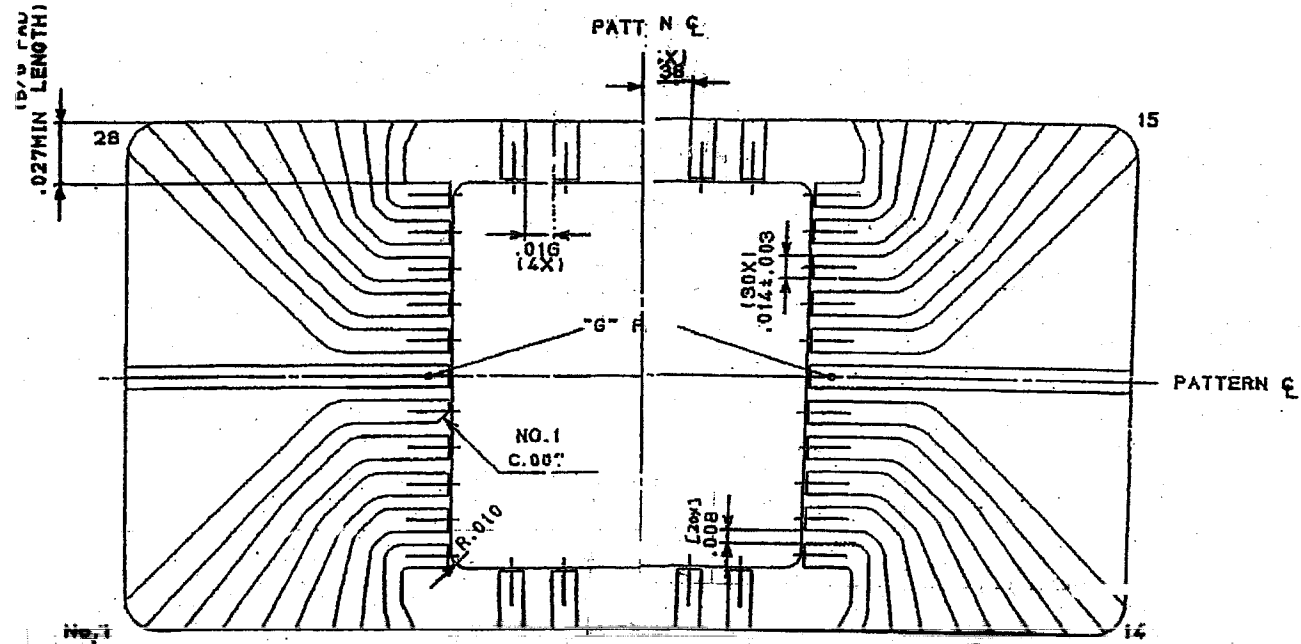


NOTES

1. GOLD PLATE 100 μ INCHES MIN OVER 80 μ INCHES MIN NICKEL.
2. "G" PAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.
3. LEAD RESISTANCE ----- 300 $m\Omega$ MAX.
4. SEAL RING AND DIE ATTACH PAD TO BE METALLIZED.



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